



Part Number:		AS4C32M16D1-5BCN-5BIN								
Part Weight:		190.4mg								
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt	PPM	
1	Substrate	HL-832NX / AUS 308	49.39	Bismaleimide Triazine	105391-33-1	6.36%	4.11	2.16%	63600	
				Epoxy resin -1	25722-66-1	6.36%	4.11	2.16%	63600	
				Epoxy resin -2	9003-36-5	6.36%	4.11	2.16%	63600	
				Inorganic Filler	21645-51-2	14.31%	9.26	4.86%	143100	
				Continuous Filament Fiber	65997-17-3	19.61%	12.69	6.66%	196100	
				Talc containing no asbestos	14807-96-6	0.48%	0.25	0.13%	4800	
				Morpholine derivative	Trade secret	0.48%	0.25	0.13%	4800	
				Barium sulfate	7727-43-7	5.40%	2.77	1.45%	54000	
				Silica, amorphous	7631-86-9	0.12%	0.06	0.03%	1200	
				Dipropylene glycol monomethyl ether	34590-94-8	2.88%	1.48	0.78%	28800	
				Epoxy resin A	Trade secret	1.56%	0.80	0.42%	15600	
				Epoxy resin B	85954-11-6	1.08%	0.55	0.29%	10800	
				Copper	7440-50-8	25.00%	8.72	4.58%	250000	
Nickel	7440-02-0	8.00%	0.19	0.10%	80000					
gold	7440-57-5	2.00%	0.04	0.02%	20000					
2	Mold compound	CEL-1802HF	111.822	Epoxy Resin 1	Trade Secret	5.50%	6.15	3.23%	55000	
				Epoxy Resin 2	Trade Secret	1.75%	1.96	1.03%	17500	
				Phenol Resin	Trade Secret	6.50%	7.27	3.82%	65000	
				Metal Hydroxide	Trade Secret	5.50%	6.15	3.23%	55000	
				Carbon Black	1333-86-4	0.20%	0.22	0.12%	2000	
				Silica	60676-86-0	79.55%	88.95	46.72%	795500	
				others	Trade Secret	1.00%	1.12	0.59%	10000	
3	Epoxy	6200	0.514	Ester Resin	Trade Secret	3.00%	0.02	0.01%	30000	
				Resin	Trade Secret	3.00%	0.02	0.01%	30000	
				Silica	Trade Secret	7.50%	0.04	0.02%	75000	
				Polyolefins	Trade Secret	27.50%	0.14	0.07%	275000	
				Epoxy Resin	Trade Secret	27.50%	0.14	0.07%	275000	
				Carbitol Acetate	112-15-2	31.50%	0.16	0.09%	315000	
4	Solder Ball	M705	20.163	Tin	7440-31-5	96.50%	19.46	10.22%	965000	
				Silver	7440-22-4	3.00%	0.60	0.32%	30000	
				Copper	7440-50-8	0.50%	0.10	0.05%	5000	
5	Gold wire	Au	0.248	gold	7440-57-5	100.00%	0.25	0.13%	1000000	
6	Die	Chip	8.263	Silicon	7440-21-3	98.00%	8.10	4.25%	980000	
				Aluminum	7429-90-5	2.00%	0.17	0.09%	20000	
			190.4				600.00%	190.40	100.00%	6000000